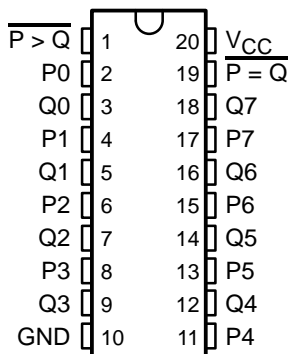


# SN54HC682, SN74HC682 8-BIT MAGNITUDE COMPARATORS

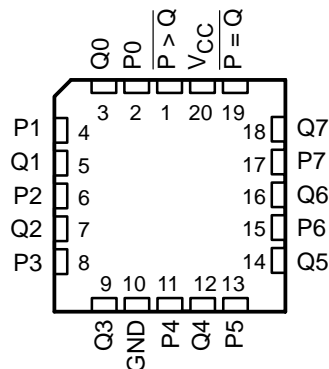
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- Wide Operating Voltage Range of 2 V to 6 V
- High-Current Outputs Drive Up To 10 LSTTL Loads
- Typical  $t_{pd} = 22$  ns
- $\pm 4$ -mA Output Drive at 5 V
- Compare Two 8-Bit Words
- 100-k $\Omega$  Pullup Resistors Are on the Q Inputs

SN54HC682 . . . J OR W PACKAGE  
SN74HC682 . . . DW OR N PACKAGE  
(TOP VIEW)



SN54HC682 . . . FK PACKAGE  
(TOP VIEW)



## description/ordering information

These magnitude comparators perform comparisons of two 8-bit binary or BCD words. The 'HC682 devices feature 100-k $\Omega$  pullup termination resistors on the Q inputs for analog or switch data.

## ORDERING INFORMATION

T <sub>A</sub>	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	PDIP – N	Tube	SN74HC682N	HC682
	SOIC – DW	Tube	SN74HC682DW	
		Tape and reel	SN74HC682DWR	
–55°C to 125°C	CDIP – J	Tube	SNJ54HC682J	SNJ54HC682J
	CFP – W	Tube	SNJ54HC682W	SNJ54HC682W
	LCCC – FK	Tube	SNJ54HC682FK	SNJ54HC682FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

## FUNCTION TABLE

DATA INPUTS P, Q	OUTPUTS	
	$\overline{P = Q}$	$\overline{P > Q}$
P = Q	L	H
P > Q	H	L
P < Q	H	H

The  $\overline{P < Q}$  function can be generated by applying  $\overline{P = Q}$  and  $\overline{P > Q}$  to a 2-input NAND gate.



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**TEXAS  
INSTRUMENTS**

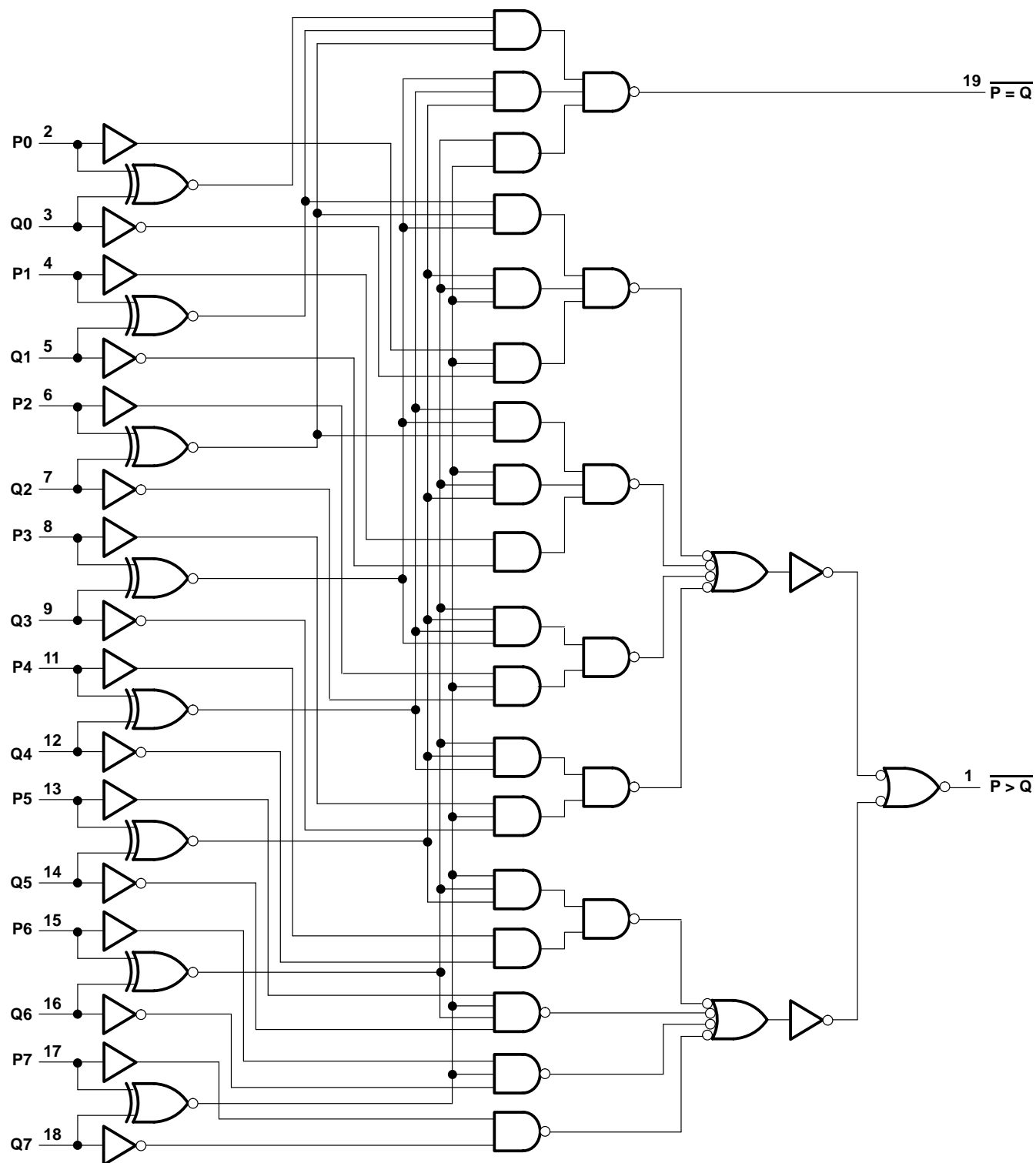
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# SN54HC682, SN74HC682 8-BIT MAGNITUDE COMPARATORS

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## logic diagram (positive logic)



**absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†**

Supply voltage range, $V_{CC}$	–0.5 V to 7 V
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see Note 1)	±20 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{CC}$ ) (see Note 1)	±20 mA
Continuous output current, $I_O$ ( $V_O = 0$ to $V_{CC}$ )	±25 mA
Continuous current through $V_{CC}$ or GND	±50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): DW package	58°C/W
N package	69°C/W
Storage temperature range, $T_{stg}$	–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.  
2. The package thermal impedance is calculated in accordance with JESD 51-7.

**recommended operating conditions (see Note 3)**

			SN54HC682			SN74HC682			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V <sub>CC</sub>	Supply voltage		2	5	6	2	5	6	V
V <sub>IH</sub>	High-level input voltage	V <sub>CC</sub> = 2 V	1.5			1.5			V
		V <sub>CC</sub> = 4.5 V	3.15			3.15			
		V <sub>CC</sub> = 6 V	4.2			4.2			
V <sub>IL</sub>	Low-level input voltage	V <sub>CC</sub> = 2 V	0.5			0.5			V
		V <sub>CC</sub> = 4.5 V	1.35			1.35			
		V <sub>CC</sub> = 6 V	1.8			1.8			
V <sub>I</sub>	Input voltage		0	V <sub>CC</sub>		0	V <sub>CC</sub>		V
V <sub>O</sub>	Output voltage		0	V <sub>CC</sub>		0	V <sub>CC</sub>		V
t <sub>t</sub>	Input transition (rise and fall) time	V <sub>CC</sub> = 2 V	1000			1000			ns
		V <sub>CC</sub> = 4.5 V	500			500			
		V <sub>CC</sub> = 6 V	400			400			
T <sub>A</sub>	Operating free-air temperature		−55	125		−40	85		°C

NOTE 3: All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

# SN54HC682, SN74HC682

## 8-BIT MAGNITUDE COMPARATORS

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**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS		V <sub>CC</sub>	T <sub>A</sub> = 25°C			SN54HC682		SN74HC682		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V <sub>OH</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OH</sub> = -20 µA	2 V	1.9	1.998		1.9		1.9		V
			4.5 V	4.4	4.499		4.4		4.4		
			6 V	5.9	5.999		5.9		5.9		
		I <sub>OH</sub> = -4 mA	4.5 V	3.98	4.3		3.7		3.84		
		I <sub>OH</sub> = -5.2 mA	6 V	5.48	5.8		5.2		5.34		
V <sub>OL</sub>	V <sub>I</sub> = V <sub>IH</sub> or V <sub>IL</sub>	I <sub>OL</sub> = 20 µA	2 V		0.002	0.1		0.1		0.1	V
			4.5 V		0.001	0.1		0.1		0.1	
			6 V		0.001	0.1		0.1		0.1	
		I <sub>OL</sub> = 4 mA	4.5 V		0.17	0.26		0.4		0.33	
		I <sub>OL</sub> = 5.2 mA	6 V		0.15	0.26		0.4		0.33	
I <sub>IH</sub>	V <sub>I</sub> = V <sub>CC</sub>		6 V		0.1	100		1000		1000	nA
I <sub>IL</sub>	V <sub>I</sub> = 0	Q inputs	6 V		-50	-90		-160		-140	µA
		All other inputs	6 V		-0.1	-100		-1000		-1000	nA
I <sub>CC</sub>	V <sub>I</sub> = V <sub>CC</sub> or 0, I <sub>O</sub> = 0		6 V		480	700		1300		1100	µA
C <sub>i</sub>			2 V to 6 V		3	10		10		10	pF

**switching characteristics over recommended operating free-air temperature range, C<sub>L</sub> = 50 pF (unless otherwise noted) (see Figure 1)**

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub>	T <sub>A</sub> = 25°C			SN54HC682		SN74HC682		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>pd</sub>	P or Q	Any	2 V		130	275		413		344	ns
			4.5 V		26	55		88		69	
			6 V		22	47		70		58	
t <sub>t</sub>		Any	2 V		38	75		110		95	ns
			4.5 V		8	15		22		19	
			6 V		6	13		19		16	

**operating characteristics, T<sub>A</sub> = 25°C**

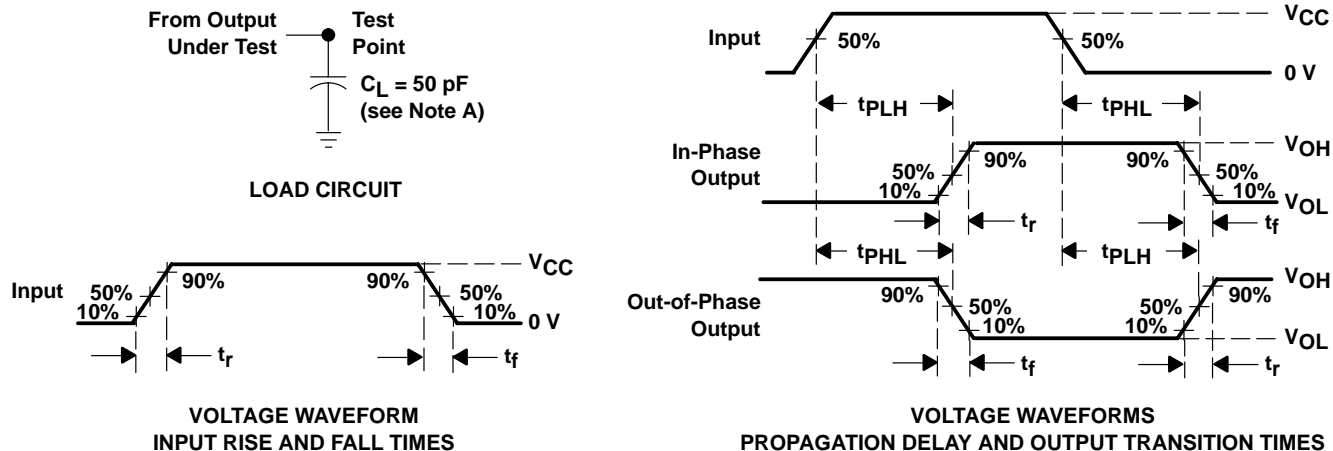
PARAMETER		TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	No load	40	pF

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# PARAMETER MEASUREMENT INFORMATION



- NOTES: A.  $C_L$  includes probe and test-fixture capacitance.  
 B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 1 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r = 6 \text{ ns}$ ,  $t_f = 6 \text{ ns}$ .  
 C. The outputs are measured one at a time with one input transition per measurement.  
 D.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

Figure 1. Load Circuit and Voltage Waveforms

## PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74HC682DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC682DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC682DWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC682DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC682DWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74HC682N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74HC682NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

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**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

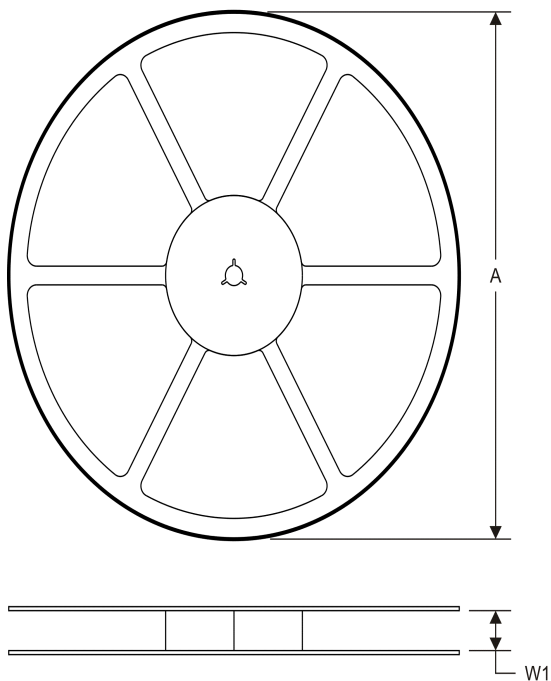
<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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## TAPE AND REEL INFORMATION

### REEL DIMENSIONS



### TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### TAPE AND REEL INFORMATION

\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC682DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC682DWR	SOIC	DW	20	2000	367.0	367.0	45.0



N (R-PDIP-T\*\*)

16 PINS SHOWN

## PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

NOTES:

- A. All linear dimensions are in inches (millimeters).  
B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).  
 The 20 pin end lead shoulder width is a vendor option, either half or full width.

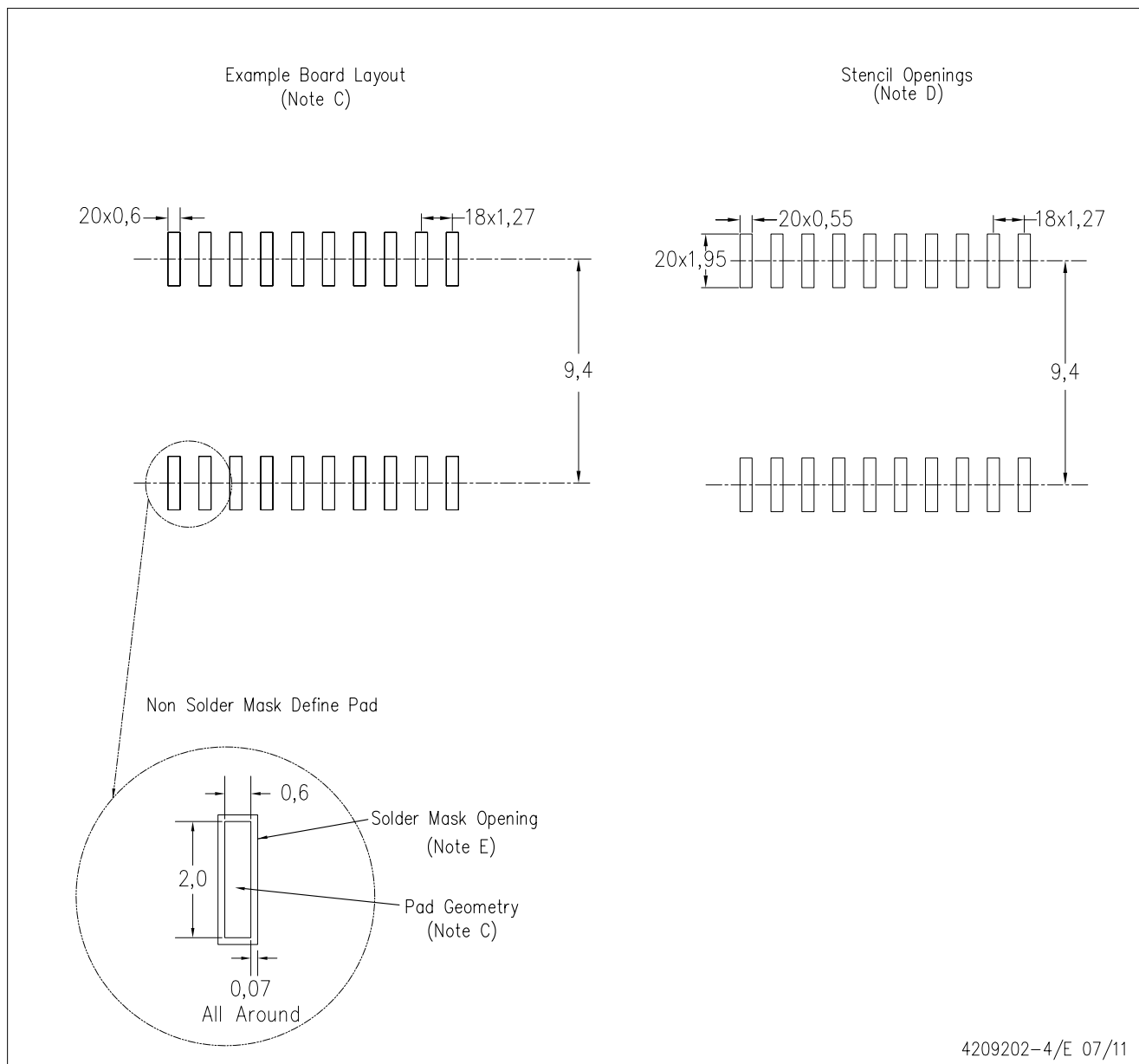
DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



DW (R-PDSO-G20)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Refer to IPC7351 for alternate board design.
  - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
  - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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